

# CORFIL® 625-1

Adhesive

Cytec Industries Inc.

## Message:

CORFIL® 625-1 potting compound is a one-part, low density material formulated for use in insert and edge filling of honeycomb core. It may also be used as a syntactic core splice adhesive. It is formulated to have low viscosity making it especially suitable for use with automated equipment. CORFIL 625-1 can be cured at either 250°F (121°C) or 350°F (177°C) with minimal to no exotherm in large applications.

### FEATURES & BENEFITS

One-part pumpable material

250°F (121°C)/ 350°F (177°C) cure

Minimal exotherm

-67 to 350°F (-55 to 177°C) service range

General Information		
Features	Low Viscosity	
	Thixotropic	
Uses	Adhesives	
	Filling Applications	
	Structural Parts	
Appearance	White	
Forms	Paste	
Processing Method	Potting	
Mechanical	Nominal Value	Unit
Compressive Strength (24°C)	20.7 to 21.4	MPa
Shear Strength <sup>1</sup> (24°C)	6.89 to 8.27	MPa
NOTE		
1.	Filled Tube	

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## Recommended distributors for this material

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